DATE:

October 17, 1996.

TO: FROM: G. Kramer/311

K. Sahu/300, I. SUBJECT: Radiation Report on: DAC8800

Project:

NASA/MSFC Support

Control #:

15373

Job #:

ER61130

cc: Jim Howard/MSFC A. Sharma/311 OFA Library/300.1

PPM-97-00T

A radiation evaluation was performed on DAC8800 (D-to-A Converter) to determine the total dose tolerance of these parts. A brief summary of the test results is provided below. For detailed information, refer to Figure 1 and Tables I through III.

The total dose testing was performed using a Co⁶⁰ gamma ray source. During the radiation testing, two parts were irradiated under bias (see Figure 1 for bias configuration) and one part was used as a control sample. The total dose radiation levels were 1, 2 and 3 krads. After the 2 krad irradiation, the parts were annealed at 25°C for 48 hours. The dose rate was between 0.015 and 0.059 krads/hour (see Table II for radiation schedule). After each radiation exposure, parts were electrically tested according to the specification limits" listed in Table III.

All parts passed all initial electrical tests.

After the 1 krad irradiation, both irradiated parts exceeded the maximum specification limit of 2,000 mA for Jech ttl and leel ttl. S/N 59 read 2.894 and 2.938 mA, respectively, and S/N 60 read 4.066 and 3.287 mA, respectively. Both parts also exceeded the maximum specification limit of 0.400 mA for loch temos and lock emos. with readings of 3.081 and 3.120 mA for S/N 59 and 3.542 and 3.536 mA, respectively, for S/N60. Both irradiated parts also marginally fell below the minimum specification limit of -0.0010% for PSSR B through PSSR H, with readings ranging from -0.0011% to -0.0013%. Both irradiated parts passed all other electrical tests at this level.

After the 2 krad irradiation, both parts continued to exceed specification limits for Iceh_ttl, Icel_ttl, Iceh emos and leek emos, with readings ranging from 6.130 to 7.592 mA for leek itl and leel itl, and from 6,066 to 5.722 mA for Icch_cmos and Iccl_cmos. In addition, both irradiated parts exceeded the maximum specification limit of 24.0 mw for s_PD, with readings of 91.1 mw for S/N 59 and 90.8 mw for S/N 60.

Both irradiated parts continued to fall below the minimum specification limit for PSSR_B through PSSR_II, with readings ranging from -0.0021% to -0.0028%, and both parts also fell below the minimum specification limit of -0,0010% for PSRR A, with readings of -0.0021%. In addition, at this irradiation level, both irradiated parts marginally exceeded specification limits for: DNL_C, DNL_E, DNL F and DNL_G for S/N 59 and DNL B. DNL D, DNL E, VZSW F, TE F, DNL F and DNL G for S/N 60. Both irradiated parts passed all other electrical tests at this level.

After annealing for 48 hours at 25°C, a very small amount of recovery was observed in Icc and other parameters.

After the 3 krad irradiation, the same degradation was observed, with approximately the same readings.

The term rads, as used in this document, means rads(SiO₂). All radiation levels cited are cumulative.

^{**} These are manufacturer's pre-irradiation data specification limits. No post-irradiation limits were provided by the manufacturer at the time these tests were performed

After annealing at 100°C for 168 hours, no rebound effects were observed.

Table III provides the data for each parameter after each uradiation exposure and annealing step.

Any further details about this evaluation can be obtained upon request. If you have any questions, please call me at (301) 731-8954.

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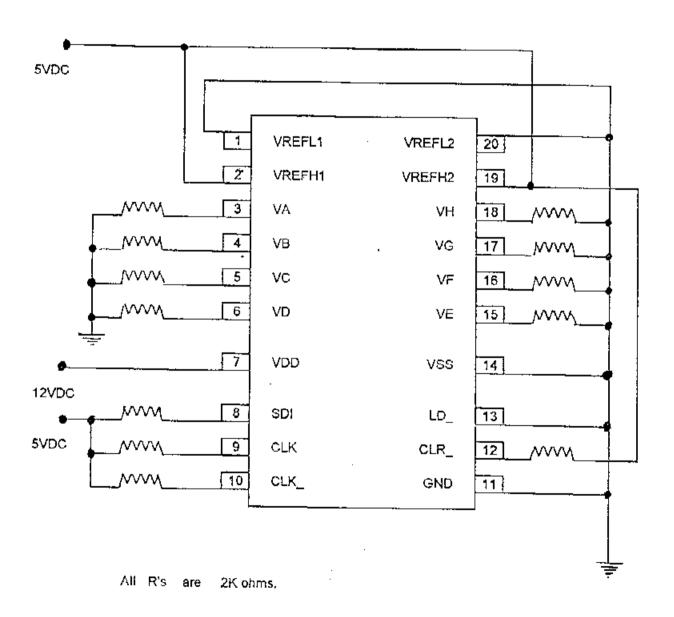
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Figure 1. Radiation Bias Circuit for DAC8800

DAC8800 OCTAL 8 BIT CMOS D/A CONVERTER

RADIATION BIAS CIRCUIT



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TABLE I, Part Information

Generic Part Numbers. DAC8800

MSFC Part Number DAC8800

MSFC Control Number: 15373

Charge Number: ER61130

Manufacturer: PMI

Lot Date Code (LDC): 9351

Quantity Tested: 3

Serial Number of Control Sample: 58

Scrial Numbers of Radiation Samples: 59, 60

Part Function: D-to-A Converter

Part Technology; CMOS

Package Style: 20-pin DIP

Test Equipment: \$-50

71-.70

Engineer: C. Nguyen

^{*} No radiation tolerance/hardness was guaranteed by the manufacturer for this part.

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TABLE II. Radiation Schedule for DAC8800

EVENT	DATE
I) INITIAL ELECTRICAL MEASUREMENTS	08/09/96
2) 1 KRAD IRRADIATION" (0.015 KRADS/HOUR) POST-1 KRAD ELECTRICAL MEASUREMENT"	09/13/96 09/26/96
3) 2 KRAD IRRADIATION (0.050 KRADS/HOUR) POST-2 KRAD ELECTRICAL MEASUREMENT	
4) 48-HOUR ANNEALING @25°C POST-48 HOUR ANNEAL ELECTRICAL MEASUREMENT	09/27/95
5) 3 KRAD IRRADIATION (0.059 KRADS/HOUR) POST-3 KRAD ELECTRICAL MEASUREMENT	. 09/30/96 10/01/96
6) 168-HOUR ANNEALING @ 100°C POST-168 HOUR ANNEAL ELECTRICAL MEASUREMENT	10/01/95 10/08/95

PARTS WERE IRRADIATED AND ANNEALED UNDER BIAS: SEE FIGURE 1.

The post-1 krad electrical measurements were delayed for 12 days due to test equipment problems. The parts were kept without bias (shorted) during this time.

TABLE IIIa: Summary of Electrical Measurements after
Total Dose Exposures and Annealing for DAC8800

													101		-000	''
	F1						Tota	l flose I	xposure	e (kræds)	Алце	aling	TDE	(krads)	Anne	aling
	Electrical			Llm/1	Ini	tial	 	1		2	48 hrs. 3	0.25°C	<u> </u>	3	168 hrs.	@ 180°C
_#	Patameters	Units	nin	max	S/N59	S/N60	S/N59	S/N60	S/N59	S/N60	S/N59	S/N60	S/N59	S/N60	S/N59	S/N60
1	Icch_ttl	mA	1	2	0.8	0.8	2.9	4.1	7.6	7.6	7.0	7.6	6.2	7.5	6.4	6.4
2	Icch_ttl	mA	0	2	0.2	0.2	2.9	3.3	6.2	6.1	5.8	6.2	6.9	7.8	6.7	6.7
3	Iceh_cmos	πιΛ	. 0	0.4	0.2	0.2	3.1	3.5	5.7	5.7	4.5	5.8	5.7	7.0	5.9	5.9
4	Icch_cmos	υιA	0	0.4	0.2	0.2	3.1	3.5	6.1	6.1	4.9	6.1	6.8	7.7	6.6	6.6
5	s PD	mw	╽	24	9	9	35	49	91	91	84	92	74	90	77	77
6	Iäh SDI	ца	-1	1	-0.2	-0.2	-0.2	-0.2	0.2	-0.2	-0.2	-0.2	-0.3	-0.2	-0.2	0.2
7	lih CLR	ED.	-1	1	0.1	0	0	0	-0.1	-fl.1	-0.2	-0.2	-0.1	-0.1	-0.2	-0.2
8	Ith CLK	ua	-1	1	-0.3	-0.2	0	0	0	-0.1	-0.3	-0.1	-0.1	-0.3	-0.2	-0.2
9	Ith LD	ua	-1	1	-0.1	-0.1	-0.2	-0.1	-0.2	-0.2	-0.2	-0.2	-0.3	-0.3	-0.3	-0.2
10	III SDI	ua	-1	1	-fl.1	-0.1	-0.1	-0.1	-0.2	-0.2	-0.1	-0.1	-0.1	-0.1	-0.1	-0,1
11	Iil_CLR	ua	-!	1	-0.4	-0.4	-0.4	-0.4	-0.3	-0.3	-0.2	-0.3	-0.2	-0.2	-0.2	0.2
12	Jil CLK	123	-1	1	-0.2	-0.2	0.2	-0.2	-0.1	-0.1	-0.1	-0.1	-0.2	-0.2	-0,2	-0.2
13	10 LD	uя	-1	1	-0.4	-0.3	-0.4	-0.3	-0.3	-0.3	-0,2	-0.3	-0.2	-0.2	-0.2	-0.2
14	PSRR_A	%	-0.00	0.001	-0.000	-0.000	-0.000	-0.000	-0.002	-0.002	-0.001	-0.002	-0.003	-0.004	-0.003	-0.003
15	PSRR_B	%	-0.00	0.001	-0.000	-0.000	-0.001	-0.001	-0.003	-0.003	-0.003	-0.003	-0.004	-0.004	-0.004	0.004
16	PSRR_C	%	-0.00	0.001	-0.001	-0.001	-0.001	-0.001	-0.003	-0.003		-0.003	-0.004	-0.004		-0.004
17	PSRR_D	%	-0.00	0.001	-0.000	-0.000	-0.001	-0.001	-0.003	-0.003		-0.003	0.004			
18	PSRR_E	%	-0.00	0.001	-0.000	-0.000	-0.001	-0.001	-0.003	-0.003	-0.003	-0.003	-0.004			
19	PSRR_F	%	-0.66	0.001	-0.000	-0.000	-0.001	-0.001	0.003	-0.003		-0.003	-0.004		-0.004	
20	PSRR_G	%	-0.00	0.001	-0.000	-0.000	0,001	100.0-	-0.003	-0.003	-0.003	-0.003	-0.004	-0.004	0.004	
21	PSRR _. H	%	-0.00	0.001	-0.000	-0.000	-0.001	-0.001	-0.000		-0,000	-0.060	-0.000	-0.000	-0.000	-0.0004
22	GSFE_A	lsb	-0.5	0.5	0	0 .	0	0	0	0	0	0	0	0.000	-0.100	0
23	VZSE A	lsbi	-0.5	0.5	0.2	0.2	0.1	0	0.2	0.2	0	0	0	0	_; <u>;</u>	0
24	TE_A	lsb	-0.5	0.5	0.1	0.1	0.2	-0.1	0	0.2	-03	0	-0.2	0	-0.2	
25	DNL_A	Isb	-1	1	0.2	0.2	0.1	0.3	0.5	0.5	0.2	0.5	0.5	1.0	0.5	0.8
26	GSFE_B	lsb	-0.5	0.5	n	U	0	0	0	- 0	0	0	0	<u> </u>	0	0
27	VZSE_B	lsh	-0.5	0.5	0	0	0	0	0.2	0.2	0	-0.1	-0.1	-3.6	-0.1	-0.1
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Notes:

^{1/} These are manufacturer's pre-irradiation data sheet specification limits. No post-irradiation limits were provided by the manufacturer at the time these tests were performed.

TABLE IIIb: **Summary of Electrical Measurements after** Total Dose Exposures and Annealing for DAC8800

											,					
							Total	Dose E	xposure	(krads)	Annealing TDE			(krads) Annealing		
	Electrical		Spec. I.	Jai./1	Init	ijal	Į.			2		48 hrs. @ 15%		3		@ 190°C
#	Parameters	Units	min	max	8/N59	S/N60	8/N59	S/N60	S/N59	S/N60	S/N59	S/N60	S/N59	8/N60	8/N59	S/N60
28	TE_B	lsb	-0,5	0.5	0.1	0	-0.1	-0.1	-0.2	-0.2	0.30	-0.3	-0.456	-0.8	-0.4	-0.4
29	DNL_B	lsb	-1	1	0.2	0.2	0.5	0.5	0.972	1,009	0.98	1.047	1.6	1.7	1.4	1.4
30	GSFE_C	lsb	-0.5	0.5	_ 0	0	0	0	0	0	0	I)	0	0	0	0
31	VZSE_C	lsh	-6.5	0,5	0	0	-0.1	0	0.2	0.2	-0.1	0	-0.1	-0.1	-0.1	1.0-
32	TE_C	lsb	-0.5	0.5	0.1	0.1	-0.1	-0.2	-0.2	-0.2	-0.3	-0.3	-0.4	-8.449	-0.393	-0.371
33	DNL_C	lsb	-1	1	0.2	0.2	0.5	0.5	1.003	0.996	1.006	1.037	1.6	1.7	1.5	1.4
34	GSFE_D	İsb	-0.5	0.5	. 0	0	Ð	0	0	0	0	0	0	0	0	0
35	VZSE_D	lsh	-0.5	0.5	0	0	0	0.1	0.3	0.3	0	-3.8	U	-0.1	-0.1	-0.1
36	TE_D	lsb	-0.5	0.5	0.1	0.1	-0.2	-0.1	-0.2	-0.2	-0.3	-0.6	-0.449	-0.464	-0.413	-0.385
37	DNL D	lsb	-1	1	0.2	0.2	0.5	0.5	1.031	1.039	1.014	1.4	1.6	1.7	1.5	1.4
38	GSFE_E	lsb	-0.5	0.5	0	a	0	0	0	0	0	0	0	0	0	U
39	VZSE_E	Lsb	-0.5	0.5	0.1	0.1	0	0	0,3	0.2	0.2	0.1	0.2	0.2	0.1	0.1
40	TE_E	lsb	-0.5	0.5	0.1	0.1	-0.1	-0.2	-0.3	-0.3	-0.3	-0,3	-0.497	-0.485	-0.466	-0.413
41	DNL, E	lsb	-1	1	0.2	0.2	0.6	0.6	1.084	1.086	1.1	1.2	1.8	1.8	1.6	1.5
42	CSFE_F	lsb	-0.5	0.5	0	U	0	0	0	0	0	0	0	0	0	0
43	VZSE_F	lsb	-0.5	0.5	0	0	0	-0.1	0.3	-3.2	0	o i	()	Ü	-2.9	0
44	TE_F	lsh	-0.5	0.5	0.1	0.1	-0.2	-0.1	-0.2	-0.7	-0.3	-0.3	-0.461	-0.479	-0.831	-0.396
45	DNL F	lsb	-1	L	0.2	0.2	0.6	0.6	1.081	1.1	1.1	1.1	1.7	1.8	1.6	1.5
46	GSFE_G	lsb	-0.5	0.5	0	D	U	0	0	0	0	0	0	ถ	- 0	0
47	VZSE_G	lsb	-0.5	0.5	U	0 .	0	-0.1	0.2	0.2	-0.1	-0.1	-ñ. 1	0	-0.1	-0.1
48	TE_G	ìsb	-0.5	0.5	0.1	0	-0.2	-0.1	-0.2	-0.2	-0.4	-0.3	-0.528	-0.482	-0.489	-0.411
49	DNL G	lsb	-i	_1	0.2	0.2	0.6	0.5	1.081	1.078	1.1	1.1	1.7	1.8	1.6	1.5
50	GSFE_H	lsb	-0.5	0.5	0	P.	U	. 0	Û	0	0	0	0	0	a	0
51	VZSE_H	lsb.	-0.5	0.5	0.2	0.2	0	0	0.3	0.3	0.1	0	0.3	0.408	0.316	0.282
52	TE_H	lsb	-0.5	0.5	0.1	0	-0.1	-0.1	-0.1	∗ 0.1	-0.1	-0.1	0.1	0.1	0.1	0.1
53	DNL H	lsb	-1	1	0.2	0.2	0.5	0.5	U.4	0.4	0.3	0.4	0.3	0.3	0.2	0.2
Note														0.0		,,,,

^{1/} These are manufacturer's pre-irradiation data sheet specification limits. No post-irradiation limits were provided by the manufacturer at the time these tests were performed.